# DIAMOND SYSTEMS CORPORATION

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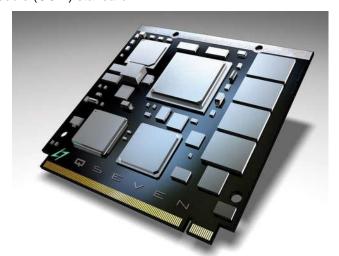
# **Diamond Systems Joins Qseven Consortium**

Leading embedded solution provider to team up Qseven™ computer-on-modules with FeaturePak™ I/O modules for rapid development of application-oriented OEM baseboards

*Mar. 2, 2010; Nuremberg, GERMANY* -- Diamond Systems Corp., a leading supplier of ruggedized single-board computers (SBCs) and I/O expansion modules targeting real-world applications, today announced that it has become a Participating Member of the Qseven Consortium, a multi-vendor standards body dedicated to advancing the Qseven computer-on-module (COM) standard.

Through its participation in the Qseven Consortium, Diamond will develop and deliver off-the-shelf and customized board-level subsystems that integrate Qseven embedded computing cores, Diamond's industry-leading analog, digital, serial, wireless, and other I/O technologies, and flexible expansion via industry-standard FeaturePak modules. These modular application-ready subsystems will assist OEMs in precisely meeting the budget, energy consumption, and performance requirements of their applications, while shortening time-to-revenue and reducing development costs and risks.

"The Qseven COM (computer-on-module) standard packs the latest low-power, embedded processors, chipsets, and standard system interfaces into a highly compact package while eliminating the need for expensive connectors that unnecessarily burden



system costs," noted Diamond Systems Founder and President Jonathan Miller. "Additionally, Qseven COMs and FeaturePak I/O modules are extremely well suited for deployment together on standard and customized application baseboards."

"We're excited to welcome Diamond Systems as the newest Participating Member of the Qseven Consortium," said Martin Danzer of Qseven Consortium Founding Member company congatec AG. "As the originator of the newly introduced FeaturePak I/O module standard, Diamond has added a significant new companion technology for adding off-the-shelf I/O modules to embedded designs based on Qseven embedded computing cores."

#### About the Qseven Consortium

The Qseven Consortium, founded in 2007 by congatec AG, Seco s.r.l. and MSC Vertriebs GmbH, is a multivendor organization dedicated to advancing use of the Qseven computer-on-module (COM) standard throughout the global embedded computing industry. Qseven COMs adhere to a standardized form-factor of 70mm x 70mm and plug into application baseboards via a single, high-speed, 230-pin MXM connector. Qseven modules integrate all core functions of an embedded computer, including CPU, memory, and interfaces for graphics, audio, mass storage, network, USB and other I/O expansion. The MXM baseboard interface connector carries all signals to and from the Qseven module, including system buses such as PCI Express and LPC, and I/O interface signals for functions such as USB, SATA, gigabit Ethernet, graphics, and audio. The Qseven Consortium currently has 21 Participating Members.

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For more information, visit www.qseven-standard.org.

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### **About Diamond**

Founded in 1989, Diamond Systems Corporation is a leading supplier of compact, rugged, wide-temperature embedded computing solutions for a wide range of applications in fixed and mobile environments. The company was an early adopter of PC/104 technology and today is one of the leading worldwide suppliers of PC/104 I/O modules and highly integrated single board computers combining CPU and data acquisition on a single board. Diamond's extensive product line includes A/D, D/A, digital I/O, serial communications, wired and wireless networking, and power supply modules as well as single-board computers and enclosures. Diamond also offers a full range of system solutions, including the capability to customize boards or systems to meet the needs of a particular application. The privately held company is based in Mountain View, California, in the heart of Silicon Valley.

For more information, visit www.diamondsystems.com or call 1-800-36-PC104.

### **Related Story**

In related news, Diamond Systems today participated in the launch of the FeaturePak Initiative. The FeaturePak specification, originated by Diamond, defines tiny, application-oriented personality modules – three-fifths the size of a credit card (depicted at right) – that snap into low-cost, low-profile sockets on single board computers (SBCs), computer-on-module (COM) baseboards, and full-custom electronic circuit boards.



